



Product End-of-Life Disassembly Instructions

Product Category: Servers

Marketing Name / Model

[List multiple models if applicable.]

HP ProLiant BL460c Gen 8

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		1
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T15

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

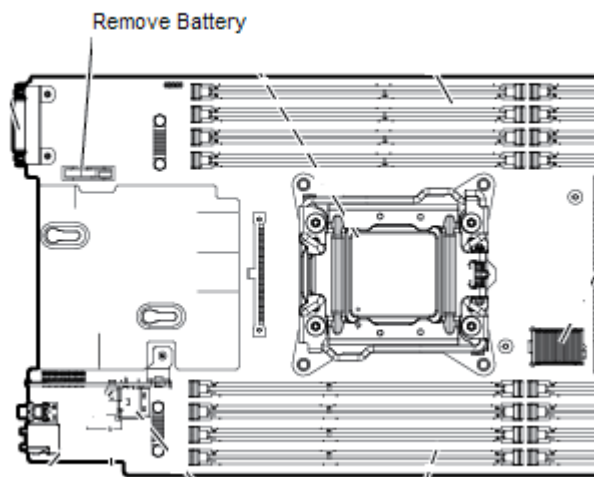
1. Click hood button and open TOP Cover.
2. Disconnect connector of super cap cable from ROC card Remove Super cap and cable.
3. Remove right and left air baffle.
4. Loose two screws from ROC card.
5. Remove ROC card.
6. Loose and remove two screws from side of HDD Cage.
7. Remove HDD Cag
8. Remove RTC Battery
9. Loose screws of MEZZ Card (if MEZZ CARD installed).
10. Remove MEZZ Card(if MEZZ CARD installed).
11. Open rear latch and remove MEZZ frame.
12. Remove BLOM card.
13. Loose and remove two screws from bottom side of base pan.
14. Remove two blue cover.
15. Remove Mother board from base pan.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Attachment 1 – System Battery Location

Attachment 2 – Super Cap location

Attachment 1



Attachment 2

